



MOTOROLA

Bi-Quinary Counter

ELECTRICALLY TESTED PER:

MPG 1678 (– 30°C to + 85°C)

The 1678 is a 4-bit counter capable of divide-by-two, divide-by-five, or divide-by-10 function. When used independently, the divide-by-two section will toggle at 350 MHz typically, while the divide-by-five section will toggle at 325 MHz typically. Clock inputs trigger on the positive going edge of the clock pulse.

Set and Reset inputs override the clock, allowing asynchronous "set" or "clear". Individual Set and common Reset inputs are provided, as well as complementary outputs for the first and fourth bits. True outputs are available at all bits.

- DC Input Factor

R	2.40
Clk	0.77
C2	1.23
S	1.00
- Power Dissipation = 750 mW typ
- f_{Tog} = 350 MHz typ

ABSOLUTE MAXIMUM RATINGS:	Symbol	Min	Max	Unit
Power Supply Voltage ($V_{CC} = 0$)	V_{CC}	– 8.0	0	Vdc
Base Input Voltage ($V_{CC} = 0$)	V_{IN}	0	V_{EE}	Vdc
Storage Temperature Range	T_{stg}	– 55	+ 125	°C
Operating Temperature Range	T_A	– 30	+ 85	°C

PIN ASSIGNMENTS

FUNCTION	DIL	BURN-IN (CONDITION C)
V_{CC1}	1	GND
C2	2	OPEN
S_2	3	GND
Q_2	4	51 Ω to V_{TT}
$\overline{Q}_3$	5	51 Ω to V_{TT}
Q_3	6	51 Ω to V_{TT}
S_3	7	GND
V_{EE}	8	V_{EE}
Reset	9	OPEN
S_1	10	GND
Q_1	11	51 Ω to V_{TT}
Q_0	12	51 Ω to V_{TT}
$\overline{Q}_0$	13	51 Ω to V_{TT}
S_0	14	GND
Clock	15	OPEN
V_{CC2}	16	GND

BURN-IN CONDITIONS:

$V_{TT} = -2.0 \text{ V MAX} / -2.2 \text{ V MIN}$
 $V_{EE} = -5.7 \text{ V MAX} / -5.2 \text{ V MIN}$

Military 1678



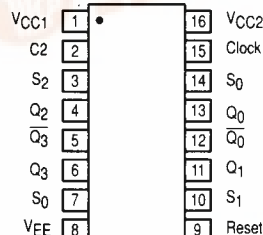
AVAILABLE AS

- 1) JAN: N/A
- 2) SMD: N/A
- 3) 883: N/A
- 4) 1678/BXA *

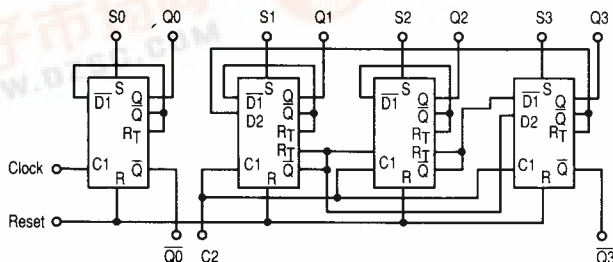
X = CASE OUTLINE AS FOLLOWS:

PACKAGE: CERPDP: E

* 883 Processing (Non-Compliant)



LOGIC DIAGRAM



TRUTH TABLE

$\bar{D}$	C	S	R	Q	$\bar{Q}$
0	0	0	0	Q_{n+1}	$\bar{Q}_{n+1}$
0	0	0	1	0	1
0	0	1	0	1	0
0	0	1	1	•	•
0	1	0	0	1	0
0	1	0	1	0	1
0	1	1	0	1	0
0	1	1	1	•	•
1	0	0	0	Q_{n+1}	$\bar{Q}_{n+1}$
1	0	0	1	0	1
1	0	1	0	1	0
1	0	1	1	•	•
1	1	0	0	0	1
1	1	0	1	0	1
1	1	1	0	1	0
1	1	1	1	•	•

• Output State Undefined

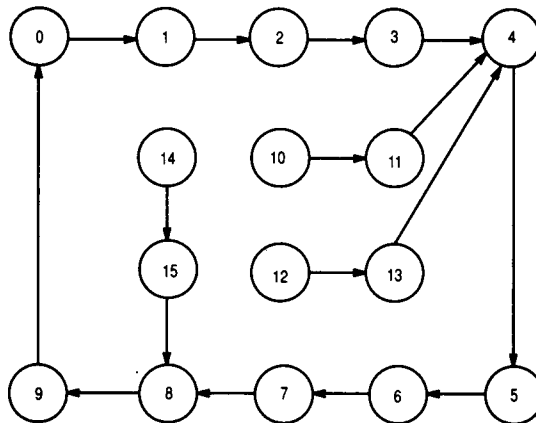
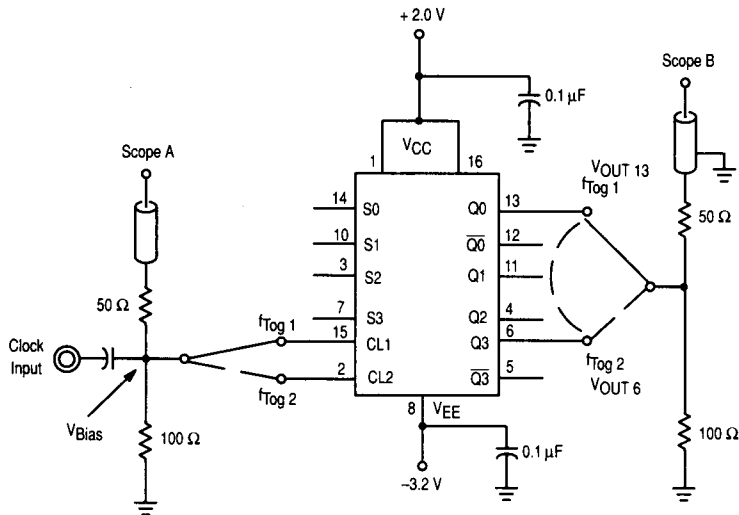


Figure 1. State Diagram

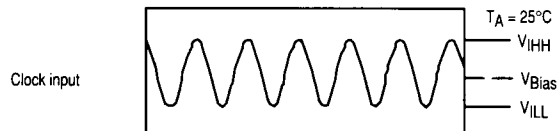
**NOTES**

1. Sine Wave generator AC coupled HP3200B or equivalent.
2. $V_{OUT} = 600$ mV min. peak to peak. Output at scope will be $1/2$ actual at V_{IN} .
3. CP = Sine Wave

Figure 2. Toggle Frequency Test Circuit

Temp.	25°C	85°C	-30°C
$V_{OUT\ 13}$	150	135	135
$V_{OUT\ 6}$	55	50	50

All in MHz min.

**Figure 3. Toggle Frequency Waveform**

Temp.	25°C	85°C	-30°C
V_{IHH}	1.11 V	1.185 V	1.041 V
V_{ILL}	0.31 V	0.337 V	0.285 V
V_{BIAS}	0.70 V	0.76 V	0.65 V

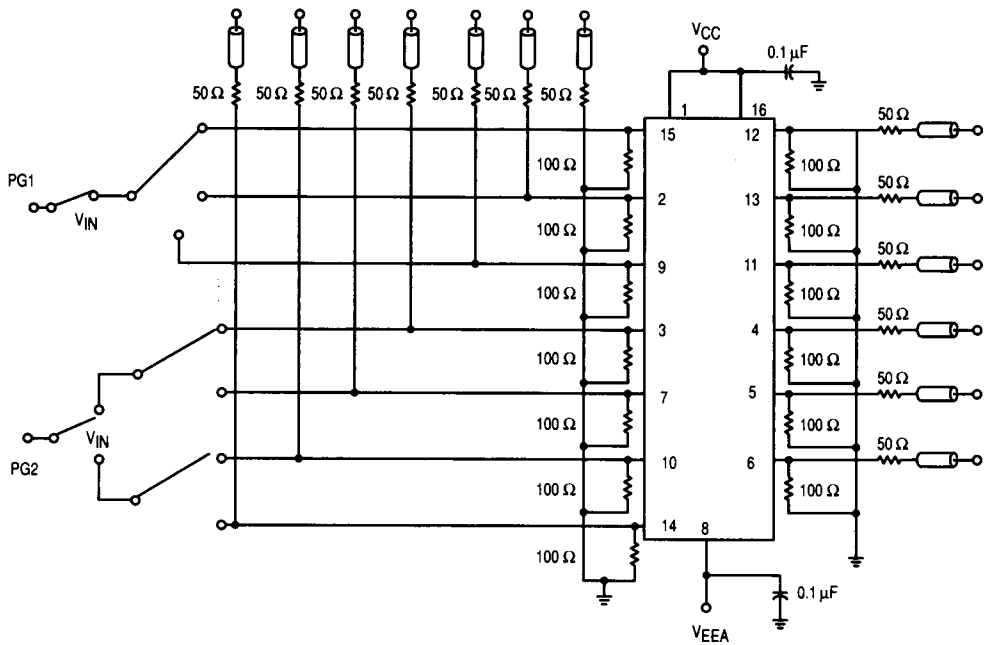
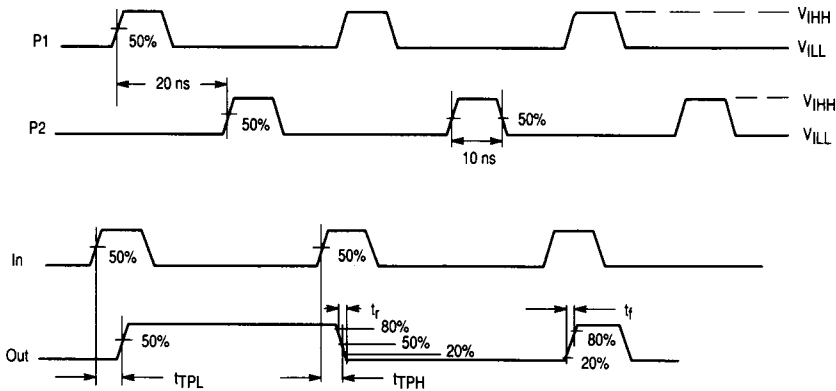


Figure 4. Switching Test Circuit

**NOTES**

1. $t_r = t_f = 1.5 \text{ ns} \pm 0.2 \text{ ns}$.
2. $f_{\text{req}} = 25 \text{ MHz}$.

Figure 5. Setup and Hold Waveforms

Temp.	25°C	85°C	-30°C
V_{IHH}	1.11 V	1.185 V	1.041 V
V_{ILL}	0.31 V	0.337 V	0.285 V

1678 QUIESCENT LIMIT TABLE

Test Temperature	Test Voltage Values (Volts)					
	V _{IH}	V _{IL}	V _{IHA}	V _{ILA}	V _{EE}	V _{EEA}
T _A = 25 °C	-0.81	-1.85	-1.095	-1.485	-5.2	-3.2
T _A = 85 °C	-0.70	-1.83	-1.025	-1.440	-5.2	-3.2
T _A = -30 °C	-0.875	-1.89	-1.180	-1.515	-5.2	-3.2

Symbol	Parameter	Limits						Units	TEST VOLTAGE APPLIED TO PINS BELOW											
		+ 25 °C		+ 85 °C		- 30 °C			Pinouts referenced are for DIL package, check Pin Assignments VCC = 0.0 V, Output Load = 50 Ω to - 2.0 V											
	Functional Parameters:	Min	Max	Subgroup 1	Min	Max	Subgroup 2	Min	Max	Subgroup 3	Min	Max	V _{IH}	V _{IL}	V _{IHA}	V _{ILA}	V _R	V _{CC}	V _{EE}	P.U.T.
V _{OH}	High Output Voltage	-0.96	-0.81	-0.89	-0.89	-0.7	-1.045	-0.875					3, 7, 9, 10, 14				4 - 6, 11 - 13	1, 16	8	4 - 6, 11 - 13
V _{OL}	Low Output Voltage	-1.85	-1.62	-1.83	-1.83	-1.575	-1.89	-1.65					7, 9, 10, 14				4 - 6, 11 - 13	1, 16	8	4 - 6, 11 - 13
V _{OHA}	High Output Voltage	-0.98	-0.81	-0.91	-0.91	-0.7	-1.065	-0.875					10		3, 7, 9, 10, 14	7, 9, 14	4 - 6, 11 - 13	1, 16	8	4 - 6, 11 - 13
V _{OLA}	Low Output Voltage	-1.85	-1.60	-1.83	-1.83	-1.555	-1.89	-1.63					10		7, 9, 14	3, 7, 9, 10, 14	4 - 6	1, 16	8	4 - 6
I _{EE}	Power Supply Drain Current	-200											2, 3, 7, 9, 10, 14, 15				1, 16	8		8
I _{INH1}	Input Current High		450										3, 7, 10, 14, 15				1, 16	8		3, 7, 9, 10, 14, 15
I _{INH2}	Input Current High		700															1, 16	8	2
I _{INH3}	Input Current High		1.0										9					1, 16	8	9
I _{INL}	Input Current Low	0.5																1, 16	8	2, 3, 7, 9, 10, 14, 15

CAUTION: This device dissipates 750 to 900 mW of power. Use heat sink if operating over 50 seconds at T_A ≥ 25°C.

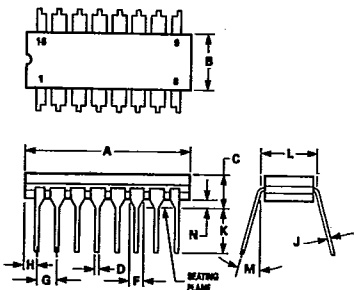
1678 QUIESCENT LIMIT TABLE

Test Temperature	Test Voltage Values (Volts)					
	V _{IH}	V _{IL}	V _{IHA}	V _{ILA}	V _{EE}	V _{VEE}
T _A = 25 °C	-0.81	-1.85	-1.095	-1.485	-5.2	-3.2
T _A = 85 °C	-0.70	-1.83	-1.025	-1.440	-5.2	-3.2
T _A = -30 °C	-0.875	-1.89	-1.180	-1.515	-5.2	-3.2

Symbol	Parameter	Limits						Units	TEST VOLTAGE APPLIED TO PINS BELOW					
	Functional Parameters:	+ 25 °C		+ 85 °C		- 30 °C			Pinouts referenced are for DIL package, check Pin Assignments Output Load = 50 Ω to GND					
		Subgroup 9		Subgroup 10		Subgroup 11								
		Min	Max	Min	Max	Min	Max							
t _{TLH}	Rise Time		2.7		3.1		2.9	ns	VIN	VOUT	VCC	VEEA	Cp1-2	P.U.T.
t _{FHL}	Fall Time		2.6		3.0		2.8	ns	14	12, 13	1, 16	8		12, 13
t _{pd}	Propagation Delay C1 Limits		2.7		3.1		2.9	ns	14	12, 13	1, 16	8		12, 13
t _{pd}	Propagation Delay C2 Limits		3.0		3.4		3.2	ns	2	4, 5, 6, 11	1, 16	8		4, 5, 6, 11
t _{Set}	Set Limits		3.7		4.1		3.9	ns	3, 7, 9, 10, 14	4 - 6, 6 - 13	1, 16	8		4 - 6, 6 - 13
t _{Reset}	Reset Limits		4.5		4.9		3.9	ns	3, 7, 9, 10, 14	4 - 6, 6 - 13	1, 16	8		4 - 6, 6 - 13
t _{Tog1}	Toggle Frequency +by 2	300		270		260		MHz			1, 16	8	15	
t _{Tog2}	Toggle Frequency +by 5	275		250		250		MHz			1, 16	8	3	

* Temperature limits are guaranteed but not tested.

**CERAMIC PACKAGE
CASE 620-09**

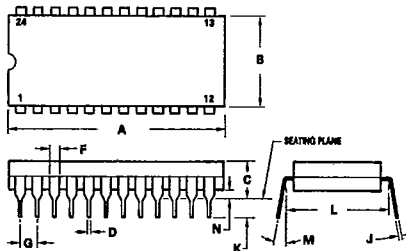


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	19.05	19.81	0.750	0.780
B	6.22	6.98	0.245	0.275
C	4.08	5.08	0.160	0.200
D	0.38	0.51	0.015	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
H	0.51	1.14	0.020	0.045
J	0.20	0.30	0.008	0.012
K	3.18	4.08	0.125	0.160
L	7.37	7.87	0.290	0.310
M	—	15°	—	15°
N	0.51	1.02	0.020	0.040

- NOTES:
- LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
 - PACKAGE INDEX: NOTCH IN LEAD NOTCH IN CERAMIC OR INK DOT.
 - DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

**L SUFFIX
CERAMIC PACKAGE
CASE 623-05**

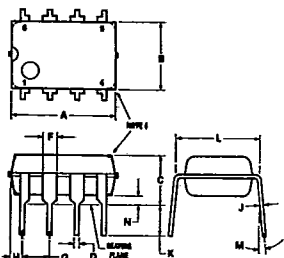
(LW SUFFIX
FOR
MC10H181
ONLY)



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.24	32.77	1.230	1.290
B	12.70	15.49	0.500	0.610
C	4.08	5.59	0.160	0.220
D	0.41	0.51	0.016	0.020
F	1.27	1.52	0.050	0.060
G	2.54 BSC		0.100 BSC	
J	0.20	0.30	0.008	0.012
K	3.18	4.08	0.125	0.160
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.27	0.020	0.050

- NOTES:
- DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
 - LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION. (WHEN FORMED PARALLEL).

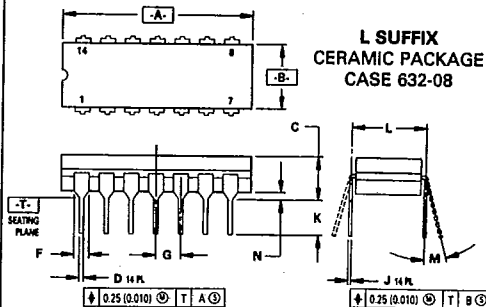
**P SUFFIX
PLASTIC PACKAGE
CASE 626-04**



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.45	10.16	0.370	0.400
B	6.10	6.80	0.240	0.269
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	—	10°	—	10°
N	0.51	0.76	0.020	0.030

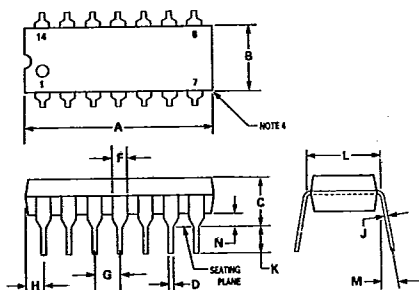
- NOTES:
- LEAD POSITIONAL TOLERANCE:
Ⓢ 0.13 (0.005) Ⓢ T | A Ⓢ B Ⓢ
 - DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 - PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
 - DIMENSIONS A AND B ARE DATUMS.
 - DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

**L SUFFIX
CERAMIC PACKAGE
CASE 632-08**



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	19.05	19.94	0.750	0.785
B	6.23	7.11	0.245	0.280
C	3.94	5.08	0.155	0.200
D	0.39	0.50	0.015	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
J	0.21	0.38	0.008	0.015
K	3.18	4.31	0.125	0.170
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

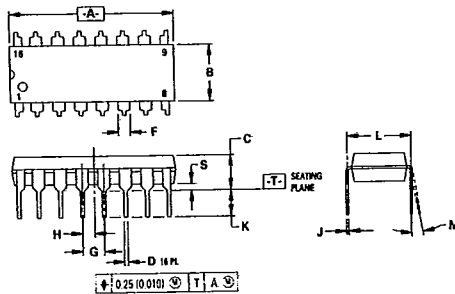
- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: INCH.
 - DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 - DIM F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	18.16	19.56	0.715	0.770
B	6.10	6.60	0.240	0.260
C	3.69	4.69	0.145	0.185
D	0.38	0.53	0.015	0.021
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	1.32	2.41	0.052	0.095
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	10°	0°	10°
N	0.39	1.01	0.015	0.039

NOTES:

- LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
- DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL.



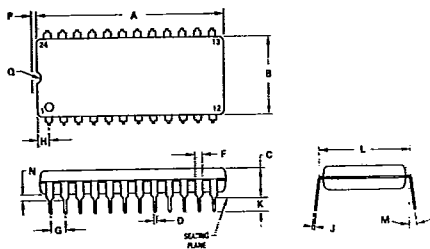
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	18.80	19.55	0.740	0.770
B	5.35	6.85	0.250	0.270
C	3.69	4.44	0.145	0.175
D	0.39	0.53	0.015	0.021
F	1.02	1.77	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	1.27 BSC		0.050 BSC	
J	0.21	0.38	0.008	0.015
K	2.80	3.30	0.110	0.130
L	7.60	7.74	0.295	0.305
M	0°	10°	0°	10°
S	0.51	1.01	0.020	0.040

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL.

P SUFFIX
PLASTIC PACKAGE
CASE 649-03

(PW SUFFIX
FOR MC10H181
ONLY)

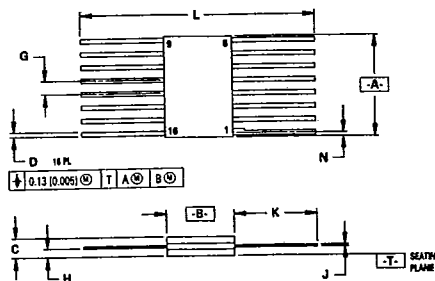


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.50	32.13	1.240	1.265
B	12.21	13.72	0.520	0.540
C	4.70	5.21	0.185	0.205
D	0.38	0.51	0.015	0.020
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	14.99	15.49	0.590	0.610
M	—	10°	—	10°
N	0.51	1.02	0.020	0.040
P	0.13	0.38	0.005	0.015
Q	0.51	0.76	0.020	0.030

NOTES:

- LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
- DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

F SUFFIX
CERAMIC PACKAGE
CASE 650-05

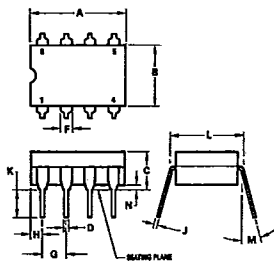


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.40	9.90	0.370	0.390
B	8.23	8.65	0.325	0.340
C	1.53	2.15	0.060	0.085
D	0.38	0.48	0.014	0.019
G	1.27 BSC		0.050 BSC	
H	0.64	0.01	0.025	0.040
J	0.11	0.17	0.004	0.007
K	6.35	9.39	0.250	0.370
L	18.93	—	0.745	—
N	—	0.50	—	0.020

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION "A" AND "B" ALLOW FOR LID MISALIGNMENT, AND GLASS MENISCUS.
- DIMENSION "H" SHALL BE MEASURED AT THE POINT OF EXIT OF THE LEAD FROM THE BODY.
- LEAD NUMBER 1 IDENTIFIED BY TAB ON LEAD OR DOT ON COVER.
- DIMENSION "J" INCLUDES SOLDER LEAD FINISH.
- LEAD NUMBERS SHOWN FOR REFERENCE ONLY.

CERAMIC PACKAGE CASE 693-02

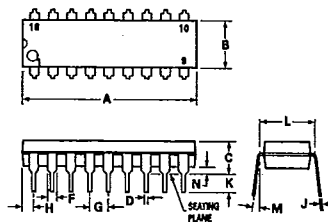


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.91	10.92	0.390	0.430
B	6.22	6.99	0.245	0.275
C	4.32	5.08	0.170	0.200
D	0.41	0.51	0.015	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
H	1.14	1.65	0.045	0.065
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	7.37	7.87	0.290	0.310
M	—	15°	—	15°
N	0.51	1.02	0.020	0.040

NOTES:

- LEADS WITHIN 0.13 mm (0.005) RAD OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
- DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

PLASTIC PACKAGE CASE 707-02

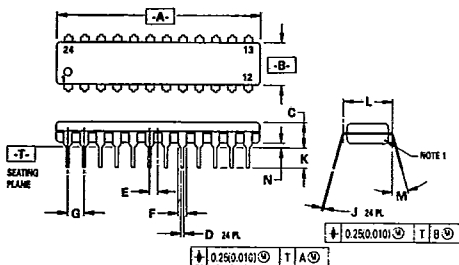


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.22	23.24	0.875	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.36	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

NOTES:

- POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25mm(0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.

P SUFFIX PLASTIC PACKAGE CASE 724-03

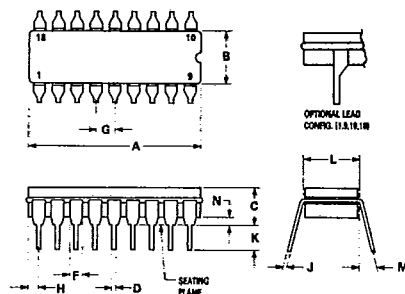


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.25	32.13	1.230	1.265
B	6.35	6.95	0.250	0.270
C	3.69	4.44	0.145	0.175
D	0.38	0.51	0.015	0.020
E	1.77 BSC		0.050 BSC	
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	0.18	0.30	0.007	0.012
J	2.80	3.55	0.110	0.140
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

NOTES:

- CHAMFERED CONTOUR OPTIONAL.
- DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.

L SUFFIX CERAMIC PACKAGE CASE 726-04

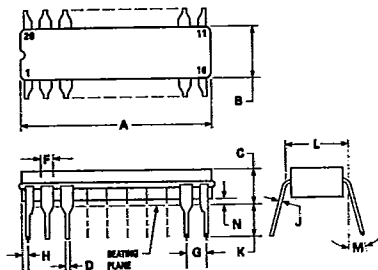


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.35	23.11	0.880	0.910
B	6.10	7.49	0.240	0.295
C	—	5.08	—	0.200
D	0.38	0.53	0.015	0.021
F	1.40	1.78	0.055	0.070
G	2.54 BSC		0.100 BSC	
H	0.51	1.14	0.020	0.045
J	0.20	0.30	0.008	0.012
K	3.18	4.32	0.125	0.170
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

NOTES:

- LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIA. AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
- DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIM "A" & "B" INCLUDES MENISCUS.
- "F" DIMENSION IS FOR FULL LEADS. "HALF" LEADS ARE OPTIONAL AT LEAD POSITIONS 1, 9, 10, AND 18.

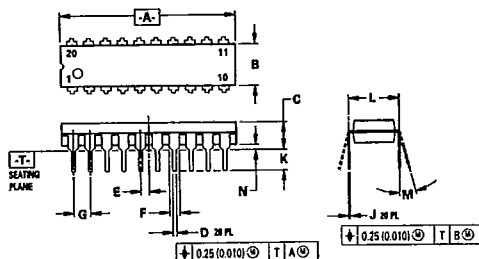
**L SUFFIX
CERAMIC PACKAGE
CASE 732-03**



DIM	MIN	MAX	MIN	MAX
A	23.08	25.15	0.940	0.990
B	6.60	7.45	0.260	0.295
C	3.81	5.08	0.150	0.200
D	0.38	0.56	0.015	0.022
E	1.40	1.65	0.055	0.065
F	2.54 BSC		0.100 BSC	
G	0.51	1.27	0.020	0.050
H	0.20	0.30	0.008	0.012
I	3.18	4.06	0.125	0.160
J	7.62 BSC		0.300 BSC	
K	0°	15°	0°	15°
L	0.25	1.02	0.010	0.040

- NOTES:
- LEADS WITHIN 0.25 mm (0.010) DIA. TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
 - DIM L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 - DIM A AND B INCLUDES MENISCUS.

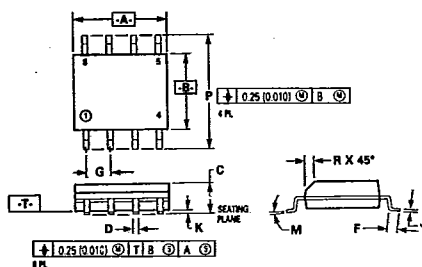
**P SUFFIX
PLASTIC PACKAGE
CASE 738-03**



DIM	MIN	MAX	MIN	MAX
A	25.65	27.17	1.010	1.070
B	6.10	6.60	0.240	0.260
C	3.81	4.57	0.150	0.180
D	0.38	0.55	0.015	0.022
E	1.27 BSC		0.050 BSC	
F	1.27	1.77	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	0.21	0.38	0.008	0.015
I	2.80	2.55	0.110	0.140
J	7.62 BSC		0.300 BSC	
K	0°	15°	0°	15°
L	0.51	1.01	0.020	0.040

- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: INCH.
 - DIMENSION "L" TO CENTER OF LEAD WHEN FORMED PARALLEL.
 - DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.

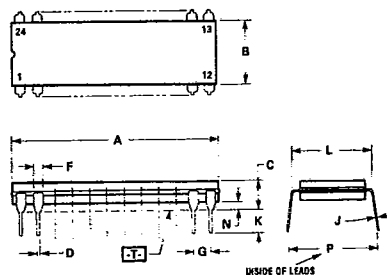
**D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751-03**



DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.196
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
E	0.40	1.25	0.016	0.049
F	1.27 BSC		0.050 BSC	
G	0.18	0.25	0.007	0.009
H	0.10	0.25	0.004	0.009
I	5.80	6.20	0.229	0.244
J	0.25	0.50	0.010	0.019

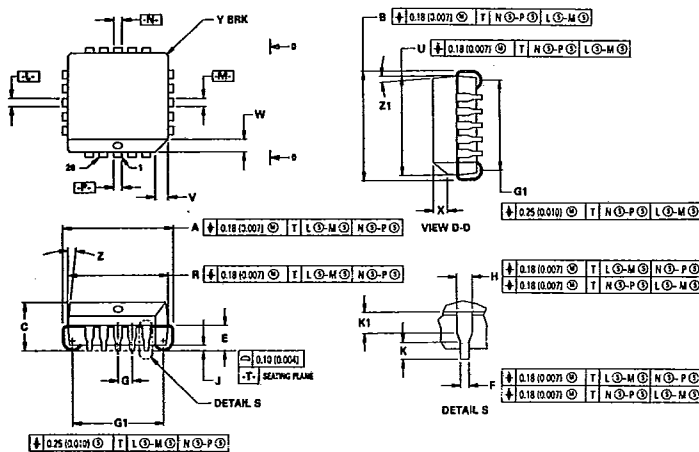
- NOTES:
- DIMENSIONS "A" AND "B" ARE DATUMS AND "T" IS A DATUM SURFACE.
 - DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIM: MILLIMETER.
 - DIMENSION "A" AND "B" DO NOT INCLUDE MOLD PROTRUSION.
 - MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

**L SUFFIX
CERAMIC PACKAGE
CASE 758-01**



DIM	MIN	MAX	MIN	MAX
A	31.50	32.84	1.250	1.285
B	7.14	7.15	0.285	0.285
C	3.68	4.44	0.145	0.175
D	0.38	0.53	0.015	0.021
E	1.14	1.57	0.045	0.062
F	2.54 BSC		0.100 BSC	
G	0.20	0.33	0.008	0.013
H	2.54	4.19	0.100	0.165
I	7.62	7.87	0.300	0.310
J	0.51	1.27	0.020	0.050
K	9.14	10.16	0.350	0.400

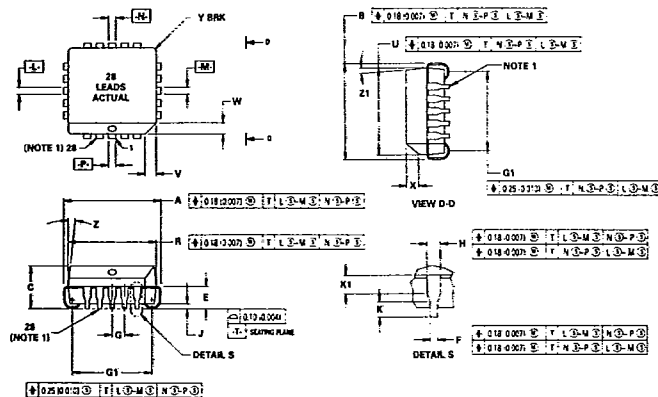
- NOTES:
- DIMENSION A IS DATUM.
 - POSITIONAL TOLERANCE FOR LEADS: 24 PLACES
 - DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
 - DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1973.



FN SUFFIX
PLASTIC PACKAGE
CASE 775-02

1. DATUMS L, M, N, AND P DETERMINED WHERE TOP OF LEAD SHOULDER EXIT PLASTIC BODY AT MOLD PARTING LINE.
2. DIM Q, TRUE POSITION TO BE MEASURED AT DATUM -T, SEATING PLANE.
3. DIM R AND U DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.25 (0.010) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.78	10.03	0.385	0.395
B	9.78	10.03	0.385	0.395
C	4.20	4.57	0.165	0.180
E	2.29	2.79	0.090	0.110
F	0.33	0.48	0.013	0.019
G	1.27 BSC		0.050 BSC	
H	0.66	0.81	0.026	0.032
J	0.51	—	0.020	—
K	0.64	—	0.025	—
R	8.89	9.04	0.350	0.356
U	8.89	9.04	0.350	0.356
V	1.07	1.21	0.042	0.048
W	1.07	1.21	0.042	0.048
X	1.07	1.42	0.042	0.056
Y	—	0.50	—	0.020
Z	2°	10°	2°	10°
G1	7.88	8.38	0.310	0.330
K1	1.02	—	0.040	—
Z1	2°	10°	2°	10°



FN SUFFIX
PLASTIC PACKAGE
CASE 776-02

- NOTES:
1. DUE TO SPACE LIMITATION, CASE 776-02 SHALL BE REPRESENTED BY A GENERAL (SMALLER) CASE OUTLINE DRAWING RATHER THAN SHOWING ALL 28 LEADS.
 2. DATUMS L, M, N, AND P DETERMINED WHERE TOP OF LEAD SHOULDER EXIT PLASTIC BODY AT MOLD PARTING LINE.
 3. DIM G1, TRUE POSITION TO BE MEASURED AT DATUM -T, SEATING PLANE.
 4. DIM R AND U DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.25 (0.010) PER SIDE.
 5. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 6. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.32	12.87	0.485	0.495
B	12.32	12.87	0.485	0.495
C	4.20	4.57	0.165	0.180
E	2.29	2.79	0.090	0.110
F	0.33	0.48	0.013	0.019
G	1.27 BSC		0.050 BSC	
H	0.66	0.81	0.026	0.032
J	0.51	—	0.020	—
K	0.64	—	0.025	—
R	11.43	11.58	0.450	0.456
U	11.43	11.58	0.450	0.456
V	1.07	1.21	0.042	0.048
W	1.07	1.21	0.042	0.048
X	1.07	1.42	0.042	0.056
Y	—	0.50	—	0.020
Z	2°	10°	2°	10°
G1	10.42	10.92	0.410	0.430
K1	1.02	—	0.040	—
Z1	2°	10°	2°	10°

in the use of insertion technology.

Limitations have been reached with insertion packages and PC board technology. Surface Mount Technology offers the opportunity to continue to advance the State-of-the-Art designs that cannot be accomplished with Insertion Technology.

Surface Mount Packages allow more optimum device performance with the smaller Surface Mount configuration. Internal lead lengths, parasitic capacitance and inductance that placed limitations on chip performance have been reduced.

The lower profile of Surface Mount Packages allows more boards to be utilized in a given amount of space. They are stacked closer together and utilize less total volume than insertion populated PC boards.

Printed circuit costs are lowered with the reduction of the number of board layers required. The elimination or reduction of the number of plated through holes in the board, contribute significantly to lower PC board prices.

Surface Mount assembly does not require the preparation of components that are common on insertion technology lines. Surface Mount components are sent directly to the assembly line, eliminating an intermediate step.

Automatic placement equipment is available that can place Surface Mount components at the rate of a few thousand per hour to hundreds of thousands of components per hour.

Surface Mount Technology is cost effective, allowing the manufacturer the opportunity to produce smaller units and offer increased functions with the same size product.

MECL AVAILABILITY IN SURFACE MOUNT

Motorola is now offering MECL 10K and MECL 10KH in the PLCC (Plastic Leaded Chip Carrier) packages.

MECL in PLCC may be ordered in conventional plastic rails or on Tape and Reel. Refer to the Tape and Reel section for ordering details.

TAPE AND REEL

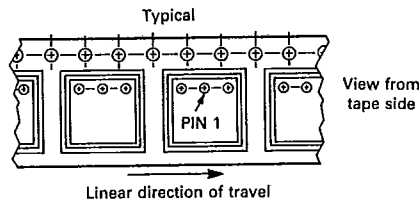
Motorola has now added the convenience of Tape and Reel packaging for our growing family of standard Integrated Circuit products. The packaging fully conforms to

peel-back cover tape.

GENERAL INFORMATION

- Reel Size 13 inch (330 mm) Suffix: R2
- Tape Width 16 mm
- Units/Reel 1000

MECHANICAL POLARIZATION



ORDERING INFORMATION

- Minimum Lot Size/Device Type = 3000 Pieces.
- No Partial Reel Counts Available.
- To order devices which are to be delivered in Tape and Reel, add the appropriate suffix to the device number being ordered.

EXAMPLE:

ORDERING CODE

MC10100FN
MC10100FNR2
MC10H100FN
MC10H100FNR2
MC12015D
MC12015DR2

SHIPMENT METHOD

Magazines (Rails)
13 inch Tape and Reel
Magazines (Rails)
13 inch Tape and Reel
Magazines (Rails)
13 inch Tape and Reel

DUAL-IN-LINE PACKAGE TO PLCC PIN CONVERSION DATA

The following tables give the equivalent I/O pinouts of Dual-In-Line (DIL) packages and Plastic Leaded Chip Carrier (PLCC) packages.

Conversion Tables

16 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
20 PIN PLCC	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20

20 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
20 PIN PLCC	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20

24 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24
28 PIN PLCC	2	3	4	5	6	7	9	10	11	12	13	14	16	17	18	19	20	21	23	24	25	26	27	28